74AHC00; 74AHCT00

Quad 2-input NAND gate

Rev. 8 — 23 April 2025 Product data sheet

1. General description

The 74AHC00; 74AHCT00 are quad 2-input NAND gates. Inputs are overvoltage tolerant. This feature allows the use of these devices as translators in mixed voltage environments.

2. Features and benefits

- Wide supply voltage range from 2.0 V to 5.5 V
- Input levels:
  - For 74AHC00: CMOS level
  - For 74AHCT00: TTL level
- Balanced propagation delays
- All inputs have Schmitt-trigger actions
- Overvoltage tolerant inputs to 5.5 V
- High noise immunity
- CMOS low power dissipation
- ESD protection:
  - HBM: ANSI/ESDA/JEDEC JS-001 class 2 exceeds 2000 V
  - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Latch-up performance exceeds 100 mA per JESD 78 Class II Level A
- Multiple package options
- Specified from -40 °C to +85 °C and from -40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74AHC00D 74AHCT00D	-40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74AHC00PW 74AHCT00PW	-40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74AHC00BQ 74AHCT00BQ	-40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1
74AHC00BZ 74AHCT00BZ	-40 °C to +125 °C	DHXQFN14	plastic, leadless dual in-line compatible thermal enhanced extreme thin quad flat package; no leads; 14 terminals; 0.4 mm pitch; body 2 mm × 2 mm × 0.48 mm	SOT8014-1

4. Functional diagram

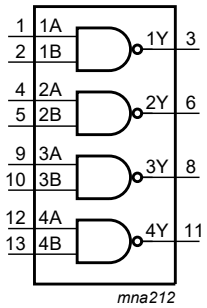


Fig. 1. Logic symbol

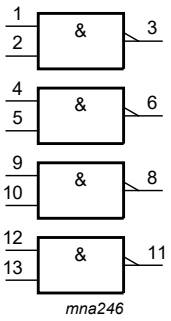


Fig. 2. IEC logic symbol

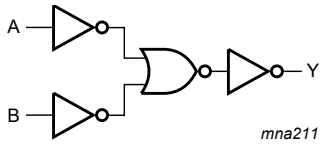
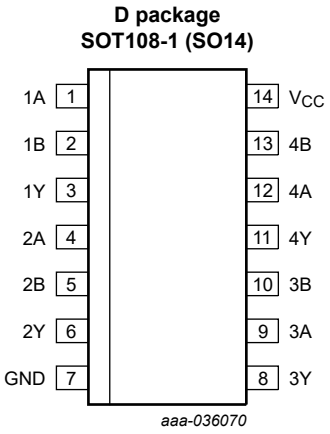
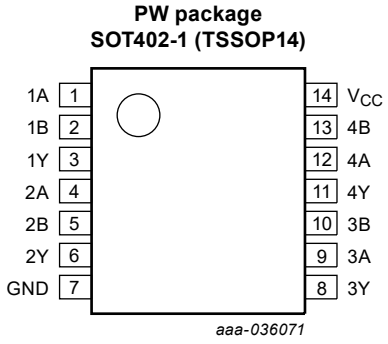


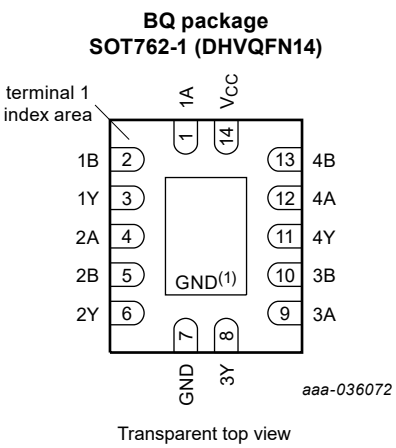
Fig. 3. Logic diagram (one gate)

5. Pinning information

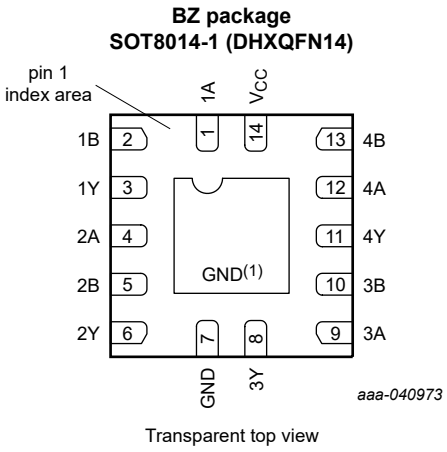
5.1. Pinning







Transparent top view



Transparent top view

(1) This is not a ground pin. There is no electrical or mechanical requirement to solder the pad. In case soldered, the solder land should remain floating or connected to GND.

5.2. Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 2A, 3A, 4A	1, 4, 9, 12	data inputs
1B, 2B, 3B, 4B	2, 5, 10, 13	data inputs
1Y, 2Y, 3Y, 4Y	3, 6, 8, 11	data outputs
GND	7	ground (0 V)
V_{CC}	14	supply voltage

6. Functional description

Table 3. Function selection

H = HIGH voltage level; L = LOW voltage level; X = don't care.

Input		Output
nA	**nB**	**nY**
L	X	H
X	L	H
H	H	L

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			-0.5	+7.0	V
V_I	input voltage			-0.5	+7.0	V
I_{IK}	input clamping current	V_I < -0.5 V	[1]	-20	-	mA
I_{OK}	output clamping current	V_O < -0.5 V or V_O > V_{CC} + 0.5 V	[1]	-20	+20	mA
I_O	output current	V_O = -0.5 V to (V_{CC} + 0.5 V)		-25	+25	mA
I_{CC}	supply current			-	+75	mA
I_{GND}	ground current			-75	-	mA
T_{stg}	storage temperature			-65	+150	°C
P_{tot}	total power dissipation	T_{amb} = -40 °C to +125 °C				
		SOT108-1 (SO14) SOT402-1 (TSSOP14) SOT762-1 (DHVQFN14)	[2]	-	500	mW
		SOT8014-1 (DHXQFN14)	[3]	-	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
[2] For SOT108-1 (SO14) package: P_{tot} derates linearly with 10.1 mW/K above 100 °C.
For SOT402-1 (TSSOP14) package: P_{tot} derates linearly with 7.3 mW/K above 81 °C.
For SOT762-1 (DHVQFN14) package: P_{tot} derates linearly with 9.6 mW/K above 98 °C.
[3] For SOT8014-1 (DHXQFN14) package: P_{tot} derates linearly with 8.7 mW/K above 121 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74AHC00			74AHCT00			Unit
			Min	Typ	Max	Min	Typ	Max	
V_{CC}	supply voltage		2.0	5.0	5.5	4.5	5.0	5.5	V
V_I	input voltage		0	-	5.5	0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	0	-	V_{CC}	V
T_{amb}	ambient temperature		-40	+25	+125	-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V_{CC} = 3.3 V ± 0.3 V	-	-	100	-	-	-	ns/V
		V_{CC} = 5.0 V ± 0.5 V	-	-	20	-	-	20	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74AHC00										
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	-	-	1.5	-	1.5	-	V
		V_{CC} = 3.0 V	2.1	-	-	2.1	-	2.1	-	V
		V_{CC} = 5.5 V	3.85	-	-	3.85	-	3.85	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	-	0.5	-	0.5	-	0.5	V
		V_{CC} = 3.0 V	-	-	0.9	-	0.9	-	0.9	V
		V_{CC} = 5.5 V	-	-	1.65	-	1.65	-	1.65	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}								
		I_O = -50 μA; V_{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I_O = -50 μA; V_{CC} = 3.0 V	2.9	3.0	-	2.9	-	2.9	-	V
		I_O = -50 μA; V_{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I_O = -4.0 mA; V_{CC} = 3.0 V	2.58	-	-	2.48	-	2.40	-	V
		I_O = -8.0 mA; V_{CC} = 4.5 V	3.94	-	-	3.80	-	3.70	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}								
		I_O = 50 μA; V_{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 50 μA; V_{CC} = 3.0 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 50 μA; V_{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 4.0 mA; V_{CC} = 3.0 V	-	-	0.36	-	0.44	-	0.55	V
		I_O = 8.0 mA; V_{CC} = 4.5 V	-	-	0.36	-	0.44	-	0.55	V
I_I	input leakage current	V_I = 5.5 V or GND; V_{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I_{CC}	supply current	V_I = V_{CC} or GND; I_O = 0 A; V_{CC} = 5.5 V	-	-	2.0	-	20	-	40	μA
C_I	input capacitance	V_I = V_{CC} or GND	-	3.0	10	-	10	-	10	pF

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74AHCT00										
V_{IH}	HIGH-level input voltage	V_{CC} = 4.5 V to 5.5 V	2.0	-	-	2.0	-	2.0	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 4.5 V to 5.5 V	-	-	0.8	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}; V_{CC} = 4.5 V								
		I_O = -50 µA	4.4	4.5	-	4.4	-	4.4	-	V
		I_O = -8.0 mA	3.94	-	-	3.80	-	3.70	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}; V_{CC} = 4.5 V								
		I_O = 50 µA	-	0	0.1	-	0.1	-	0.1	V
		I_O = 8.0 mA	-	-	0.36	-	0.44	-	0.55	V
I_I	input leakage current	V_I = 5.5 V or GND; V_{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	µA
I_{CC}	supply current	V_I = V_{CC} or GND; I_O = 0 A; V_{CC} = 5.5 V	-	-	2.0	-	20	-	40	µA
ΔI_{CC}	additional supply current	per input pin; V_I = V_{CC} - 2.1 V; I_O = 0 A; other pins at V_{CC} or GND; V_{CC} = 4.5 V to 5.5 V	-	-	1.35	-	1.5	-	1.5	mA
C_I	input capacitance	V_I = V_{CC} or GND	-	3.0	10	-	10	-	10	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

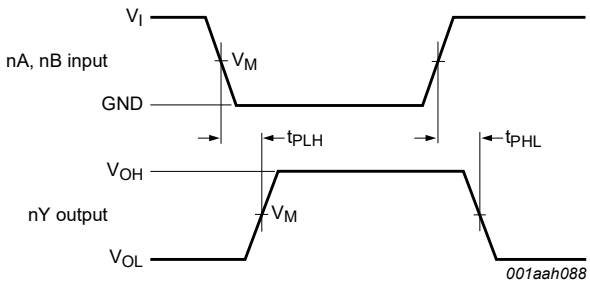
Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 5.

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	Min	Max	
74AHC00										
t_{pd}	propagation delay	nA, nB to nY; see Fig. 4 [2]								
		V_{CC} = 3.0 V to 3.6 V								
		C_L = 15 pF	-	4.5	7.9	1.0	9.5	1.0	10.0	ns
		C_L = 50 pF	-	6.0	11.4	1.0	13.0	1.0	14.5	ns
		V_{CC} = 4.5 V to 5.5 V								
		C_L = 15 pF	-	3.2	5.5	1.0	6.5	1.0	7.0	ns
		C_L = 50 pF	-	4.5	7.5	1.0	8.5	1.0	9.5	ns
C_{PD}	power dissipation capacitance	C_L = 50 pF; f_i = 1 MHz; V_I = GND to V_{CC} [3]	-	7.0	-	-	-	-	-	pF

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	Min	Max	
74AHCT00										
t_{pd}	propagation delay	nA, nB to nY; see Fig. 4 [2]								
		V_{CC} = 4.5 V to 5.5 V								
		C_L = 15 pF	-	3.3	6.9	1.0	8.0	1.0	9.0	ns
		C_L = 50 pF	-	4.5	7.9	1.0	9.0	1.0	10.0	ns
C_{PD}	power dissipation capacitance	C_L = 50 pF; f_i = 1 MHz; V_I = GND to V_{CC} [3]	-	7.0	-	-	-	-	-	pF

[1] Typical values are measured at nominal supply voltage (V_{CC} = 3.3 V and V_{CC} = 5.0 V).
[2] t_{pd} is the same as t_{PLH} and t_{PHL}.
[3] C_{PD} is used to determine the dynamic power dissipation (P_D in µW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
C_L = output load capacitance in pF;
V_{CC} = supply voltage in V;
N = number of inputs switching;
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

10.1. Waveforms

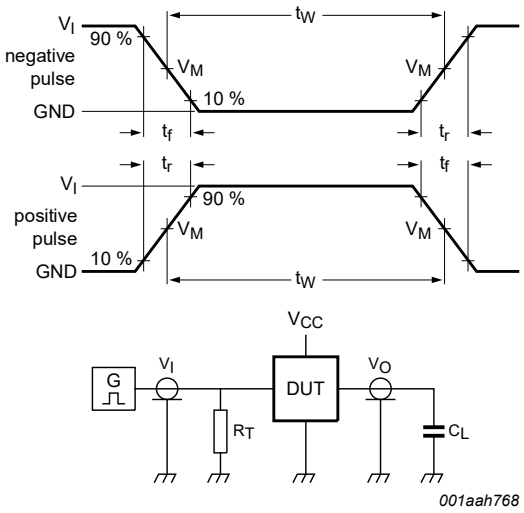


Measurement points are given in Table 8.
V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig. 4. Input to output propagation delays

Table 8. Measurement points

Type	Input	Output
	V_M	V_M
74AHC00	0.5 × V_{CC}	0.5 × V_{CC}
74AHCT00	1.5 V	0.5 × V_{CC}



Test data is given in Table 9.

Definitions test circuit:

R_T = termination resistance should be equal to output impedance Z_o of the pulse generator;

C_L = load capacitance including jig and probe capacitance.

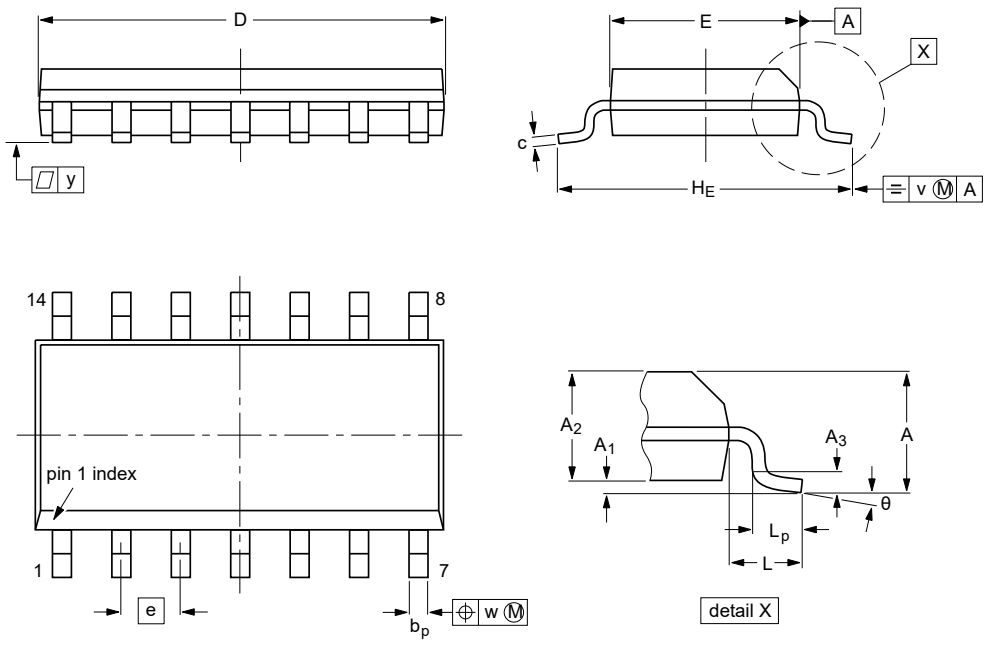
Fig. 5. Test circuit for measuring switching times

Table 9. Test data

Type	Input		Load	Test
	V_I	t_r, t_f	C_L	
74AHC00	V_{CC}	≤ 3.0 ns	15 pF, 50 pF	t_{PLH}, t_{PHL}
74AHCT00	3.0 V	≤ 3.0 ns	15 pF, 50 pF	t_{PLH}, t_{PHL}

11. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm **SOT108-1**



Dimensions (inch dimensions are derived from the original mm dimensions)

Unit		A	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	v	w	y	θ
mm	max	1.75	0.25			0.51	0.25	8.75	4.0		6.2		1.27				8°
	nom				0.25					1.27		1.05		0.2	0.25	0.1	
	min		0.10	1.25		0.31	0.10	8.55	3.8		5.8		0.4				0°
inches	max	0.069	0.010			0.020	0.010	0.344	0.16		0.244		0.05				8°
	nom				0.01					0.05		0.041		0.008	0.01	0.004	
	min		0.004	0.049		0.012	0.004	0.337	0.15		0.228		0.016				0°

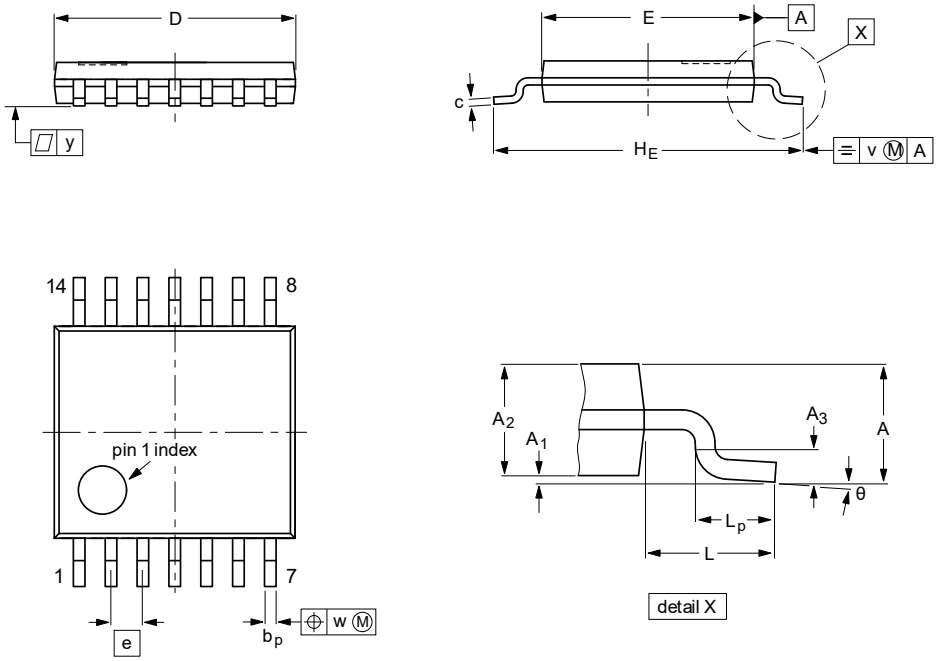
Note
1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

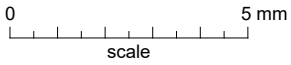
sot108-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT108-1		MS-012				~~03-02-19~~ 23-10-27

Fig. 6. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm **SOT402-1**





Dimensions (mm are the original dimensions)

Unit		A	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	v	w	y	θ
mm	max	1.20	0.15	1.05		0.30	0.2	5.1	4.5		6.6		0.75				8°
	nom				0.25					0.65		1		0.2	0.1	0.1	
	min		0.05	0.80		0.19	0.09	4.9	4.3		6.2		0.45				0°

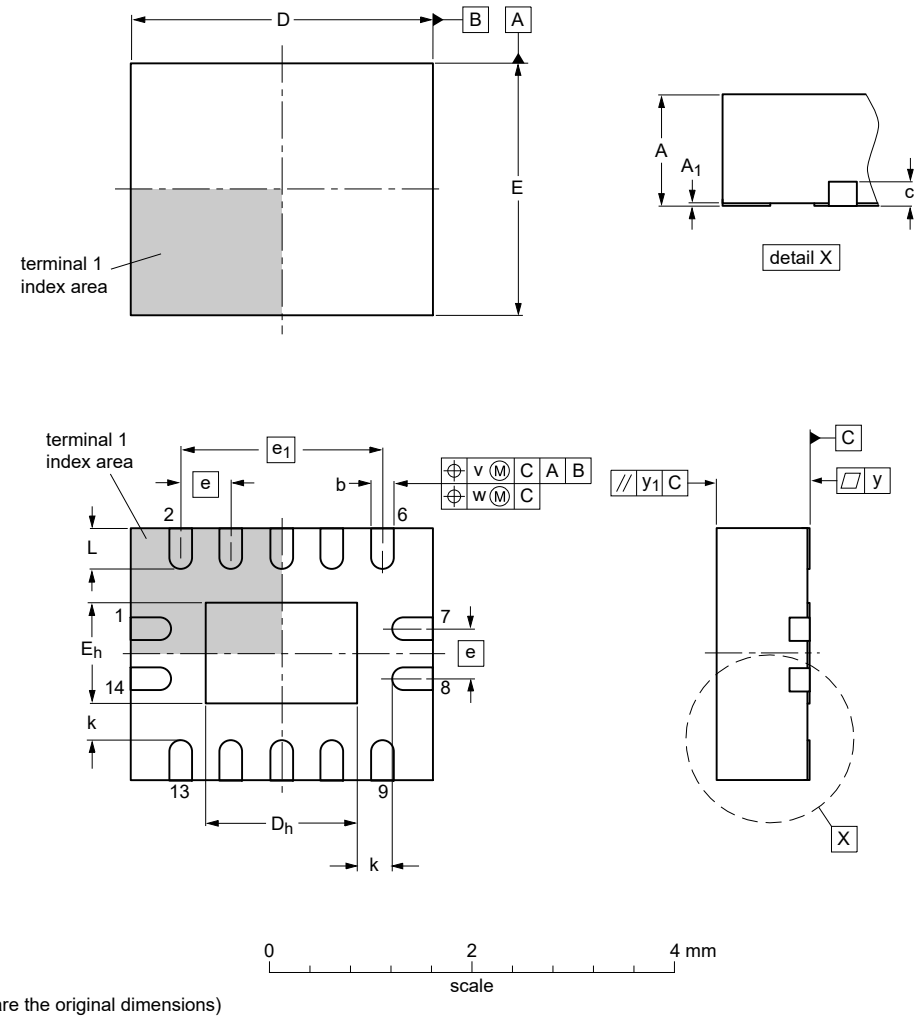
Note
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot402-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT402-1		MO-153				~~03-02-18~~ 23-10-27

Fig. 7. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm **SOT762-1**



Dimensions (mm are the original dimensions)

Unit		$A^{(1)}$	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	k	L	v	w	y	y_1
	max	1	0.05	0.30		3.1	1.65	2.6	1.15				0.5				
mm	nom		0.02	0.25	0.2	3.0	1.50	2.5	1.00	0.5	2		0.4	0.1	0.05	0.05	0.1
	min		0.00	0.18		2.9	1.35	2.4	0.85			0.2	0.3				

Note

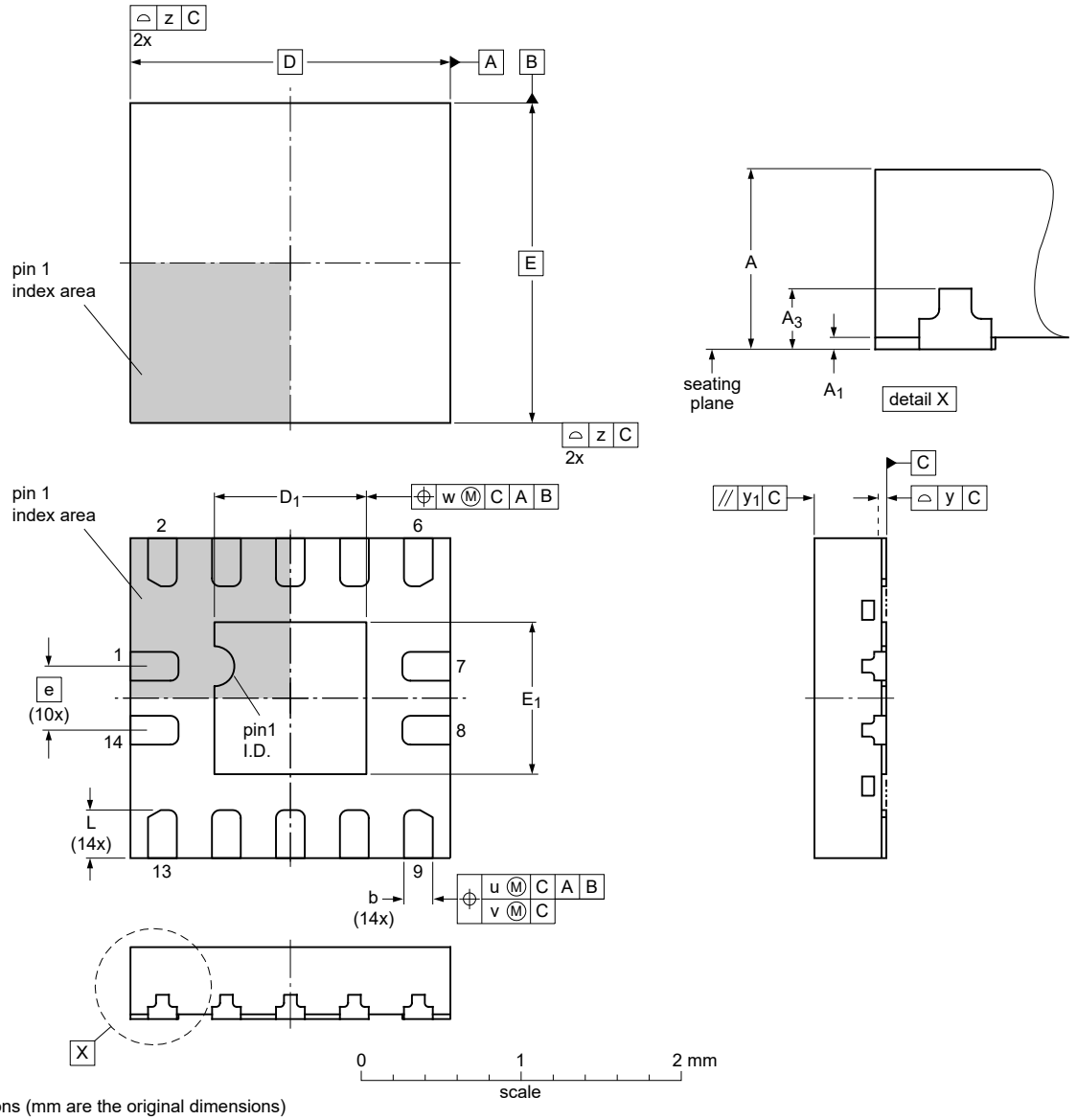
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot762-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT762-1		MO-241				~~15-04-10~~ 15-05-05

Fig. 8. Package outline SOT762-1 (DHVQFN14)

DHXQFN14: plastic, leadless dual in-line compatible thermal enhanced extreme thin quad flat package; no leads; 14 terminals; 0.4 mm pitch; body 2 mm x 2 mm x 0.48 mm **SOT8014-1**



Dimensions (mm are the original dimensions)

Unit	A	A_1	A_3	b	D	D_1	E	E_1	e	k	L	u	v	w	y	y_1	z
max	0.48	0.05	0.15 (typ)	0.23	2.0	1.00	2.0	1.00	0.4	0.2	0.35	0.1	0.05	0.1	0.05	0.05	0.05
mm nom	0.45	0.02		0.18		0.95		0.95			0.30						
min	0.42	0.00		0.13		0.90		0.90			0.25						

sot8014-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT8014-1						~~20-09-18~~ 20-09-22

Fig. 9. Package outline SOT8014-1 (DHXQFN14)

12. Abbreviations

Table 10. Abbreviations

Acronym	Description
ANSI	American National Standards Institute
CDM	Charge Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
ESDA	ElectroStatic Discharge Association
HBM	Human Body Model
JEDEC	Joint Electron Device Engineering Council
TTL	Transistor-Transistor Logic

13. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT00 v.8	20250423	Product data sheet	-	74AHC_AHCT00 v.7
Modifications:	• Type numbers 74AHC00BZ and 74AHCT00BZ (SOT8014-1/DHXQFN14) added.			
74AHC_AHCT00 v.7	20240115	Product data sheet	-	74AHC_AHCT00 v.6
Modifications:	• Section 2: ESD specification updated according to the latest JEDEC standard. • Fig. 6, Fig. 7: Aligned SO and TSSOP package outline drawings to JEDEC MS-012 and MO-153.			
74AHC_AHCT00 v.6	20230901	Product data sheet	-	74AHC_AHCT00 v.5
Modifications:	• Section 2: ESD specification updated according to the latest JEDEC standard.			
74AHC_AHCT00 v.5	20200526	Product data sheet	-	74AHC_AHCT00 v.4
Modifications:	• The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. • Legal texts have been adapted to the new company name where appropriate. • Section 1 and Section 2 updated. • Table 4: Derating values for P_{tot} total power dissipation have been updated. • Package outline drawing of SOT762-1 (Fig. 8) updated.			
74AHC_AHCT00 v.4	20080428	Product data sheet	-	74AHC_AHCT00 v.3
Modifications:	• Table 6: the conditions for input leakage current have been changed.			
74AHC_AHCT00 v.3	20080108	Product data sheet	-	74AHC_AHCT00 v.2
74AHC_AHCT00 v.2	19990923	Product specification	-	74AHC_AHCT00 v.1
74AHC_AHCT00 v.1	19981209	Product specification	-	-

14. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 23 April 2025